

Silicone Heat Transfer Compound



860

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- High thermal conductivity
- High dielectric constant
- High dissipation factor
- Use with heat sinks or metal chassis
- Will not dry or harden
- Contains zinc oxides and polydimethyl siloxane
- [Non-silicone](#) version available

Designed for use in transferring heat away from electrical and electronic devices such as; transistors, power diodes, semi-conductors, ballast's and thermocouple wells. High thermal conductivity, high dielectric constant, high dissipation factor, use with heat sinks or metal chassis, will not dry or harden. Contains zinc oxide and polydimethyl siloxane.

Specifications

Physical Properties	Test Method	Non Silicone 8610	Silicone 860
Appearance	Visual	Off white / smooth paste	White paste
Consistency	ASTM D 217	310-320	
Specific Gravity @ 25°C (77°F)		2.5 min	2.3 min
Bleed % 24 hours @ 200°C	FTM-321	1.0% max	2.0% max
Evaporation 24 hours @ 200°C	FTM-321	2.0% max	2.0% max
Dropping Point	ASTM D-566	> 500°F (260°C)	> 500°F (260°C)
Min. operating temp.		-40°F/-40°F	55°F/48°C
Max. operating temp.		200°C	200°C (consistent) 300°C (intermittent)
Electrical Properties	Test Method	Non Silicone 8610	Silicone 860
Thermal Conductivity	Hot Wire Method Heat Flow #36 °C	0.773 W/m•K	0.657 W/m•K
Dielectric Strength (0.05I gap)	ASTM D-149	350 V/MIL	400 V/MIL
Dielectric Constant @ 1000 Hz	ASTM D- 150	4.4	3.81
Dissipation Factor @ 1000 Hz	ASTM D 150	0.0021	0.0032
Resistivity @ 21°C	ASTM D 150	6.38 x 10 ¹³ Ohm•cm	1.5 x 10 ¹⁵ Ohm•cm

Available Sizes

Catalog Number	Sizes Available	Description
860-4G	4g x 100	Pail of 100 singles
860-60G	60g (2 oz)	Jar
860-150G	150g (5 oz)	Tube
860-1P	1 pint (2.5 lbs)	Tub